
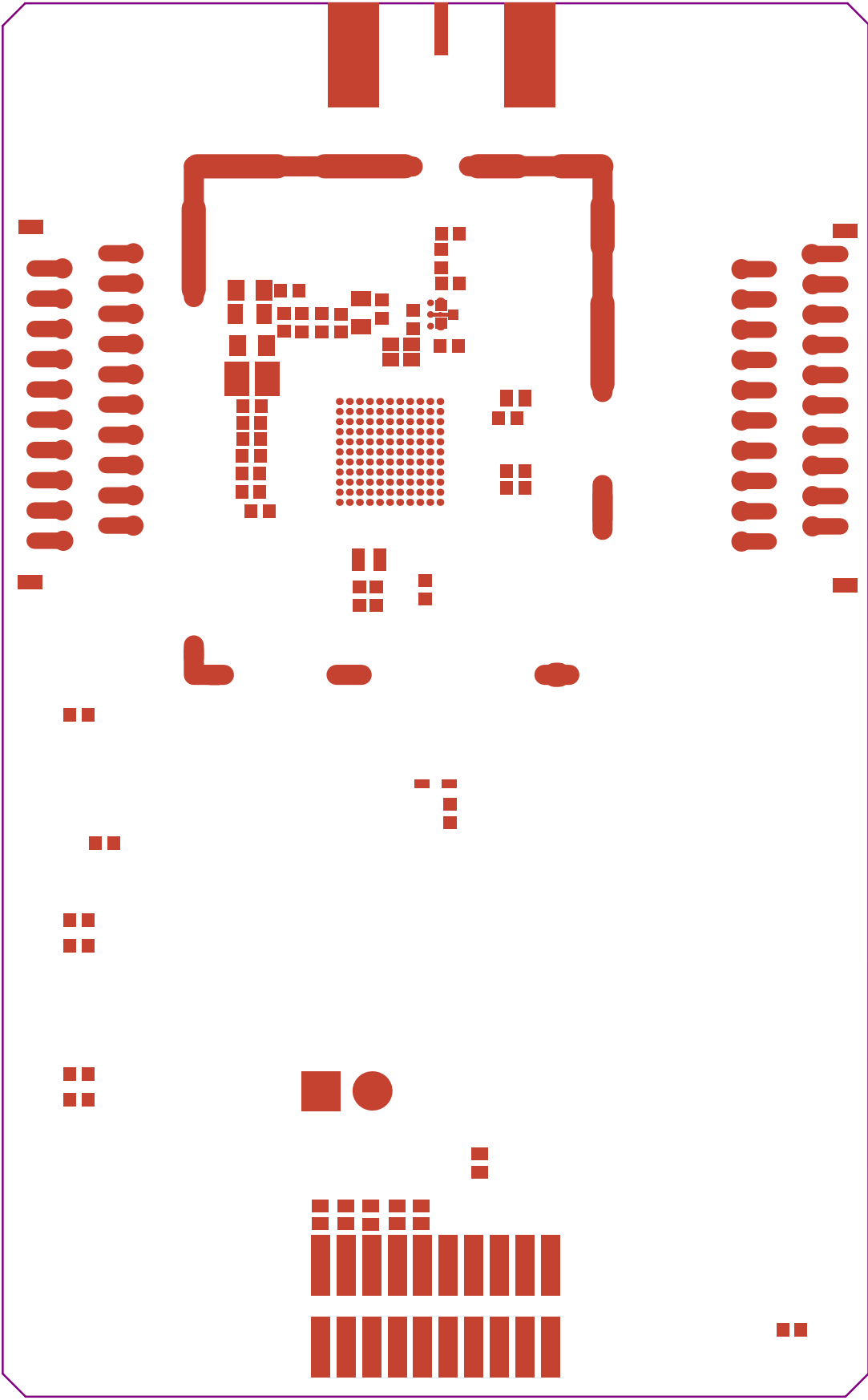

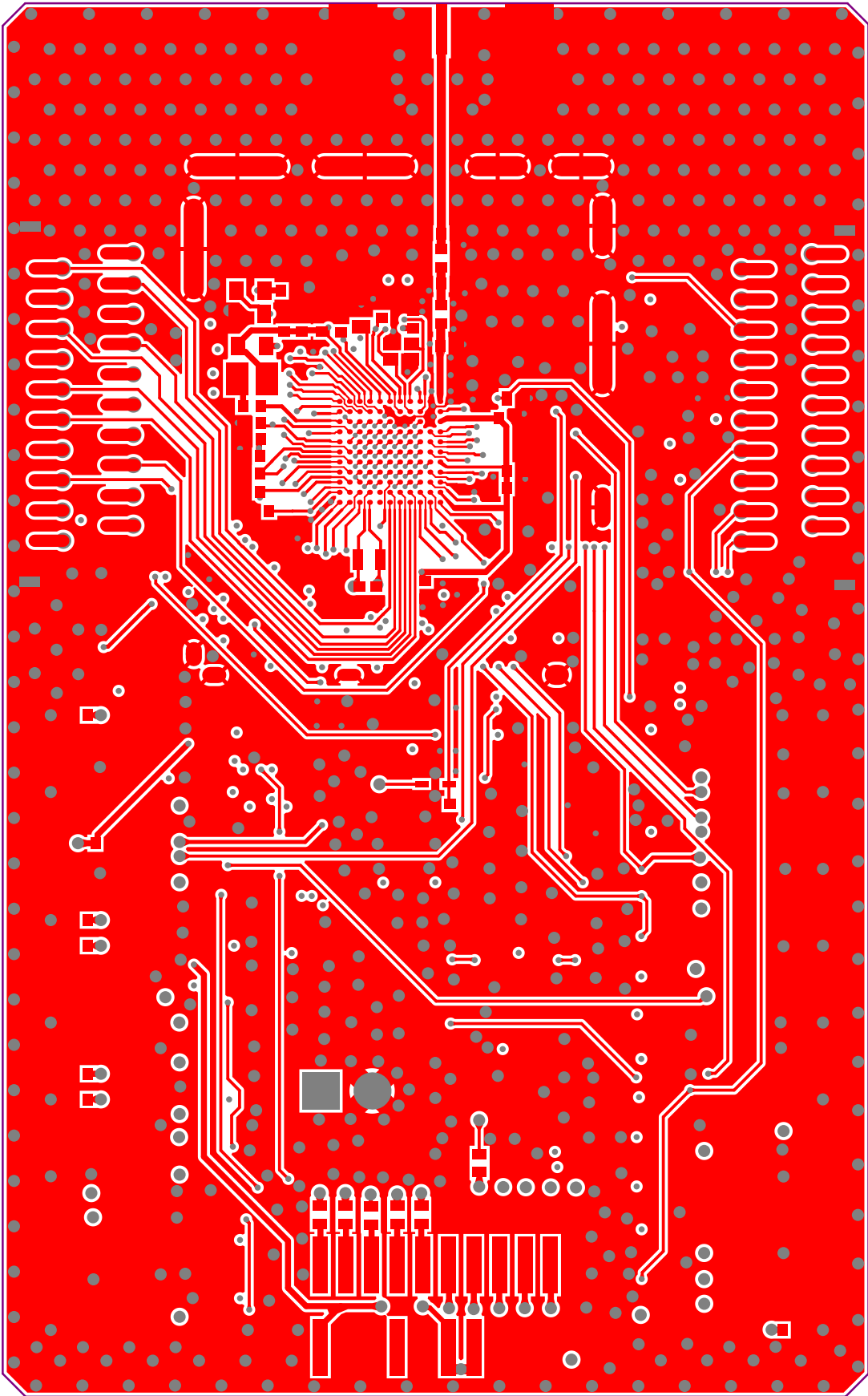



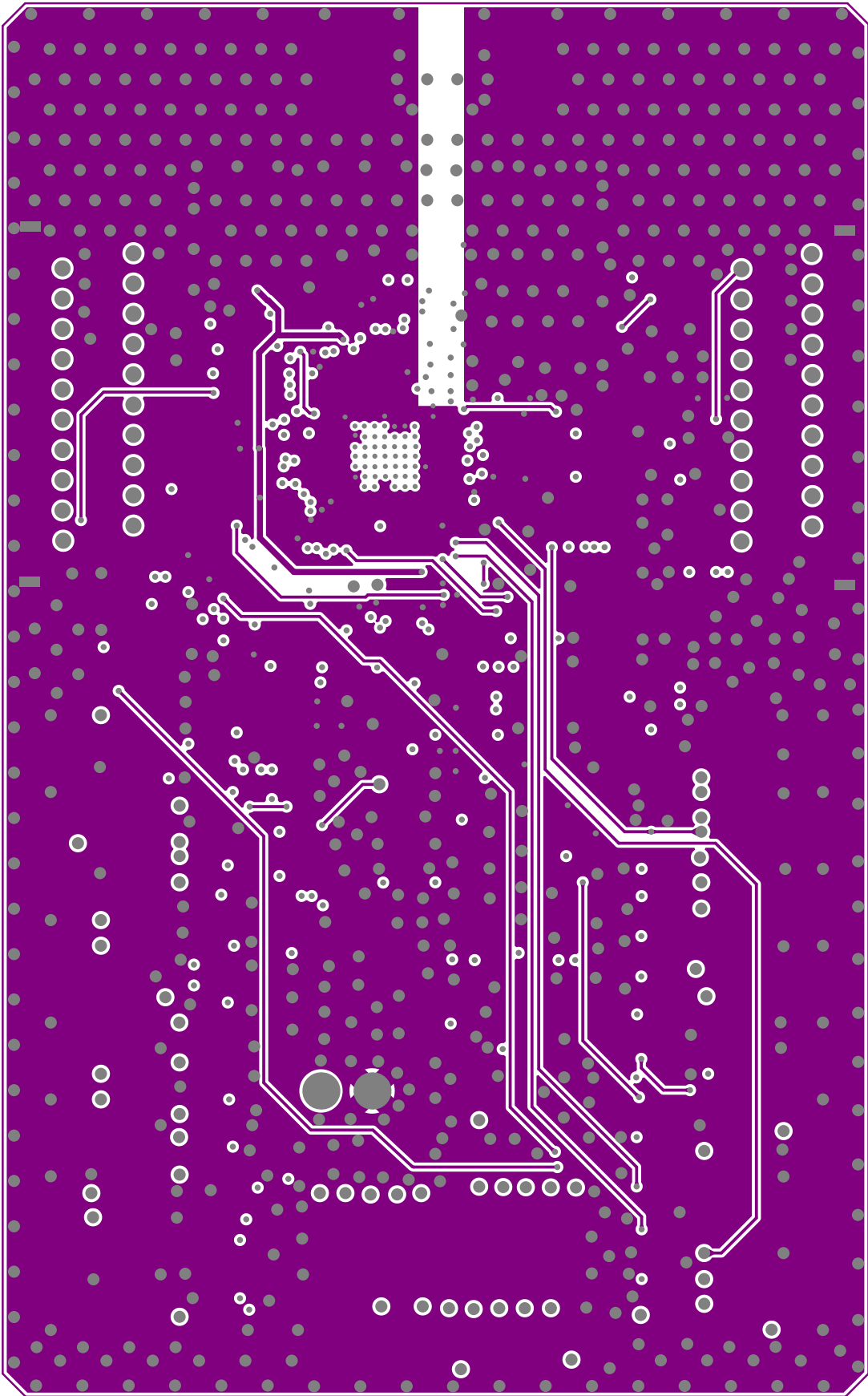
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




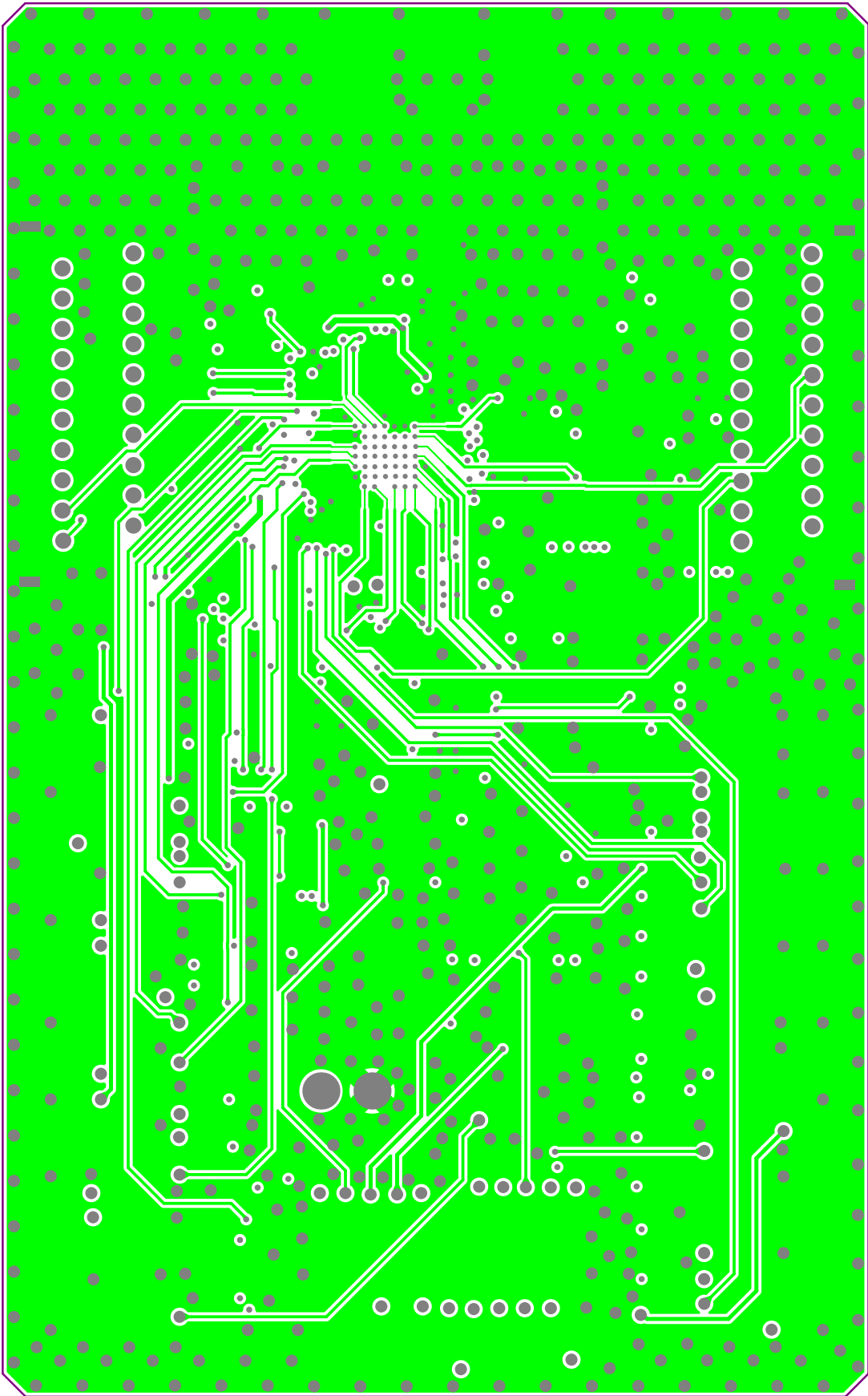
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




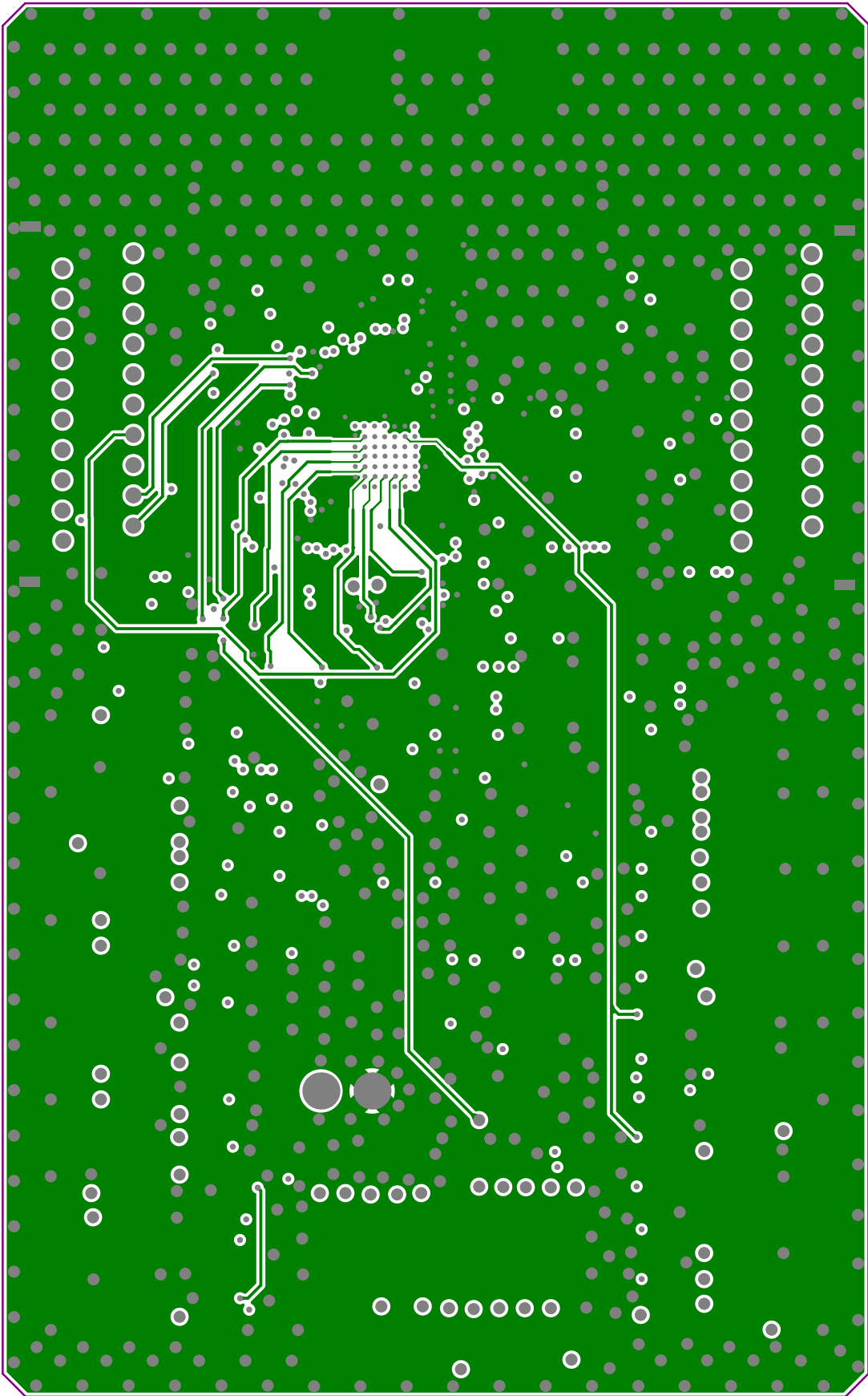
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




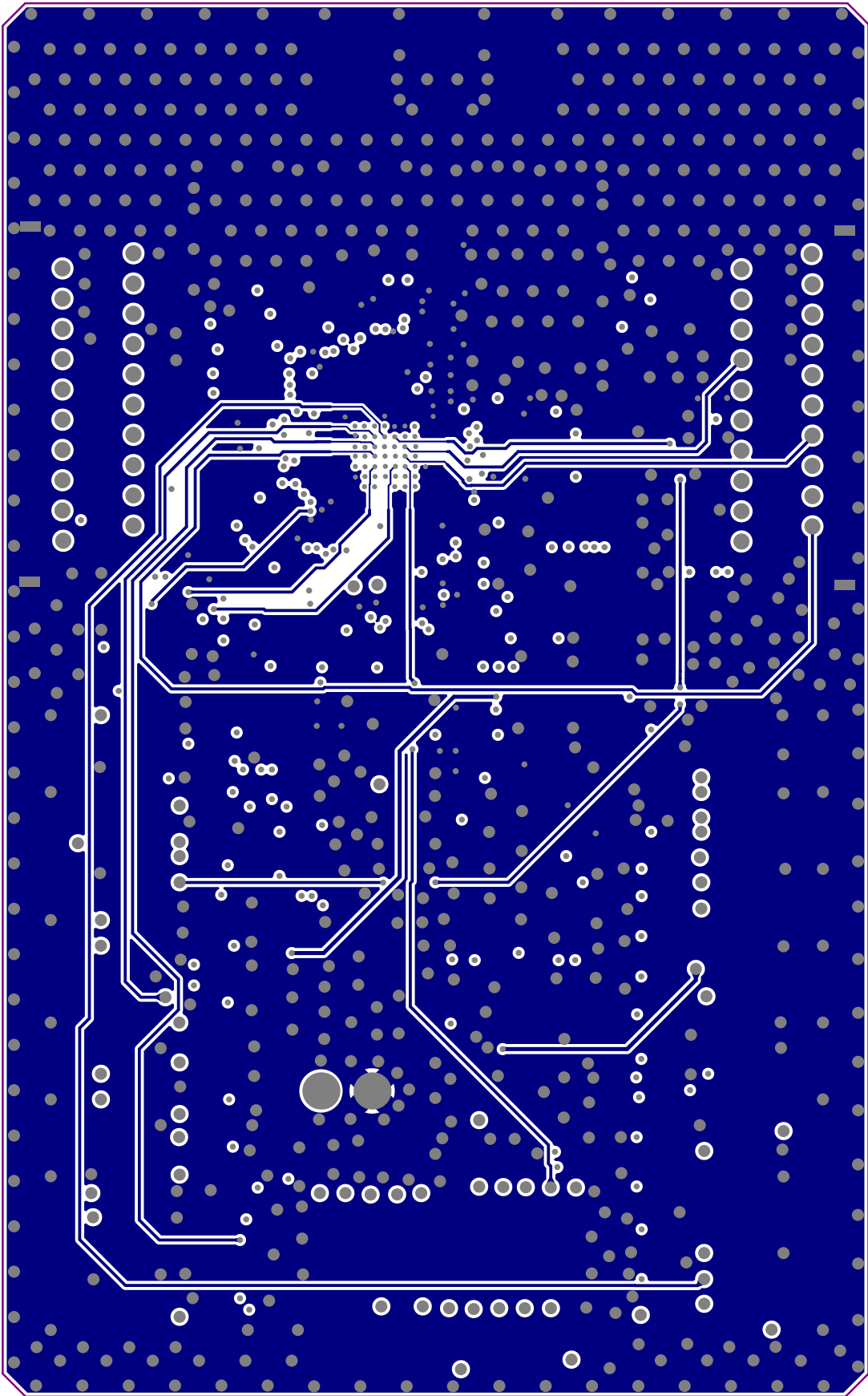
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Int1 (Sign)	Gerber: .G1	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




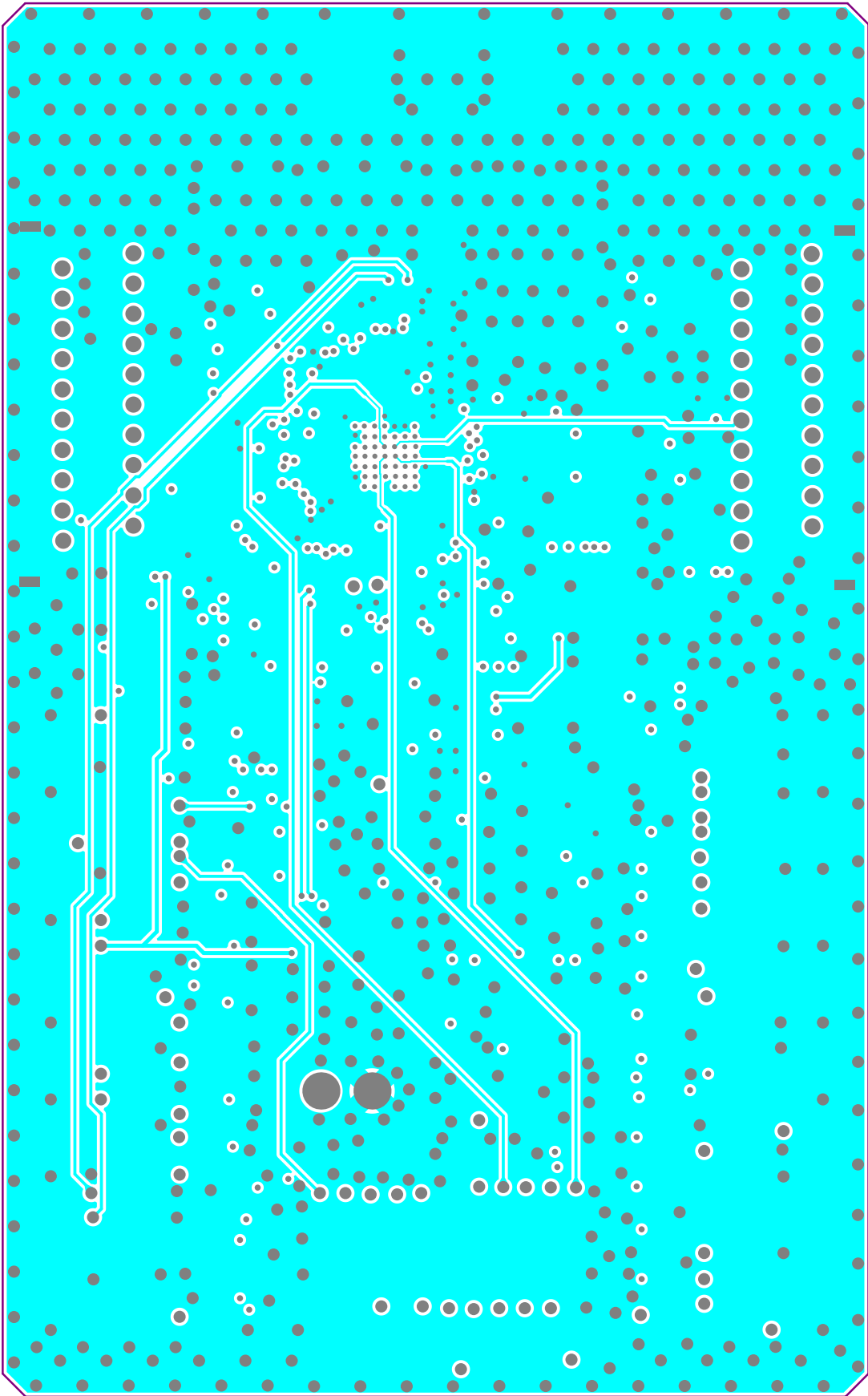
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Int2 (Sign)	Gerber: .G2	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




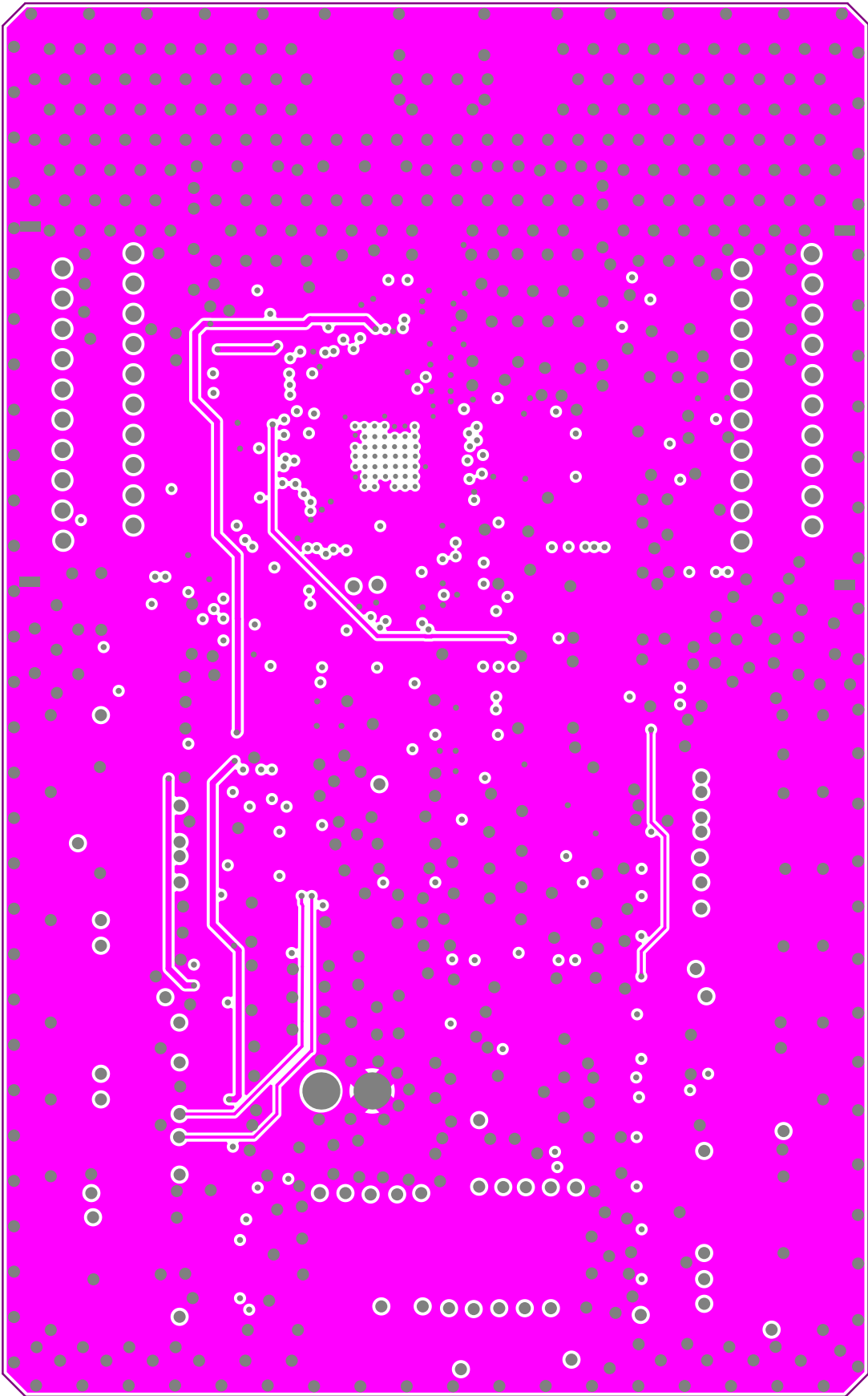
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Int3 (Sign)	Gerber: .G3	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




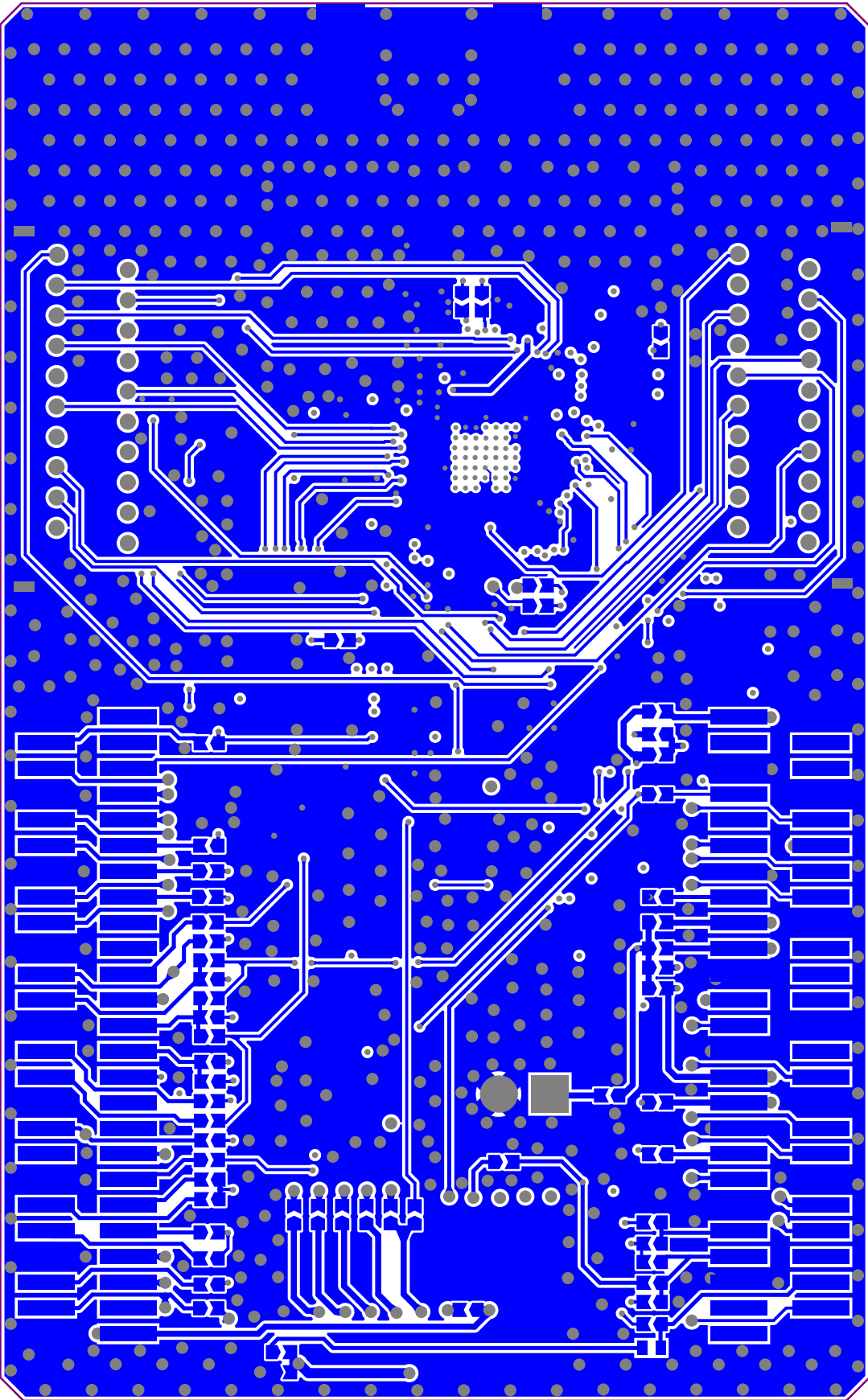
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Int4 (Sign)	Gerber: .G4	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




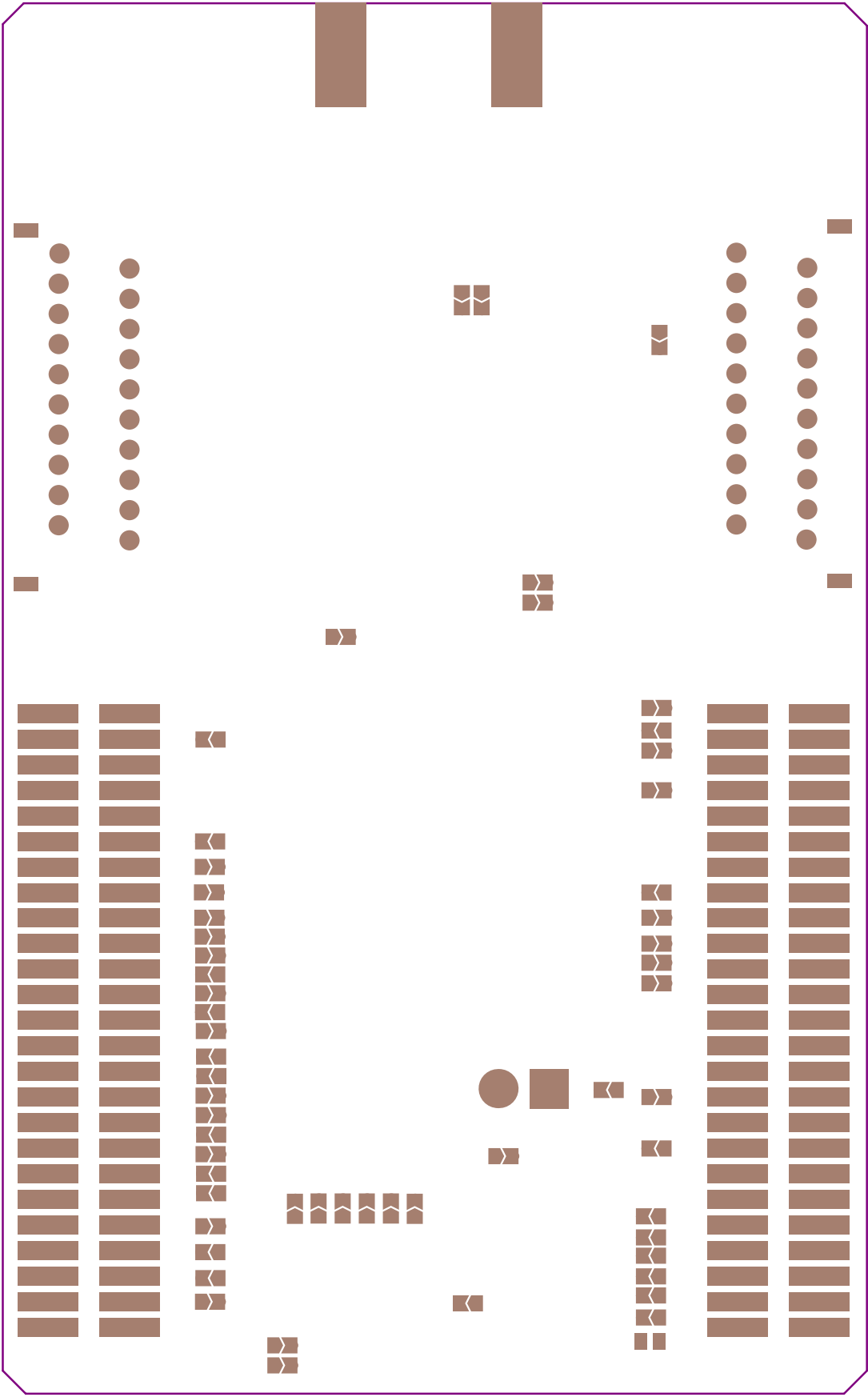
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Int5 (Sign)	Gerber: .G5	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




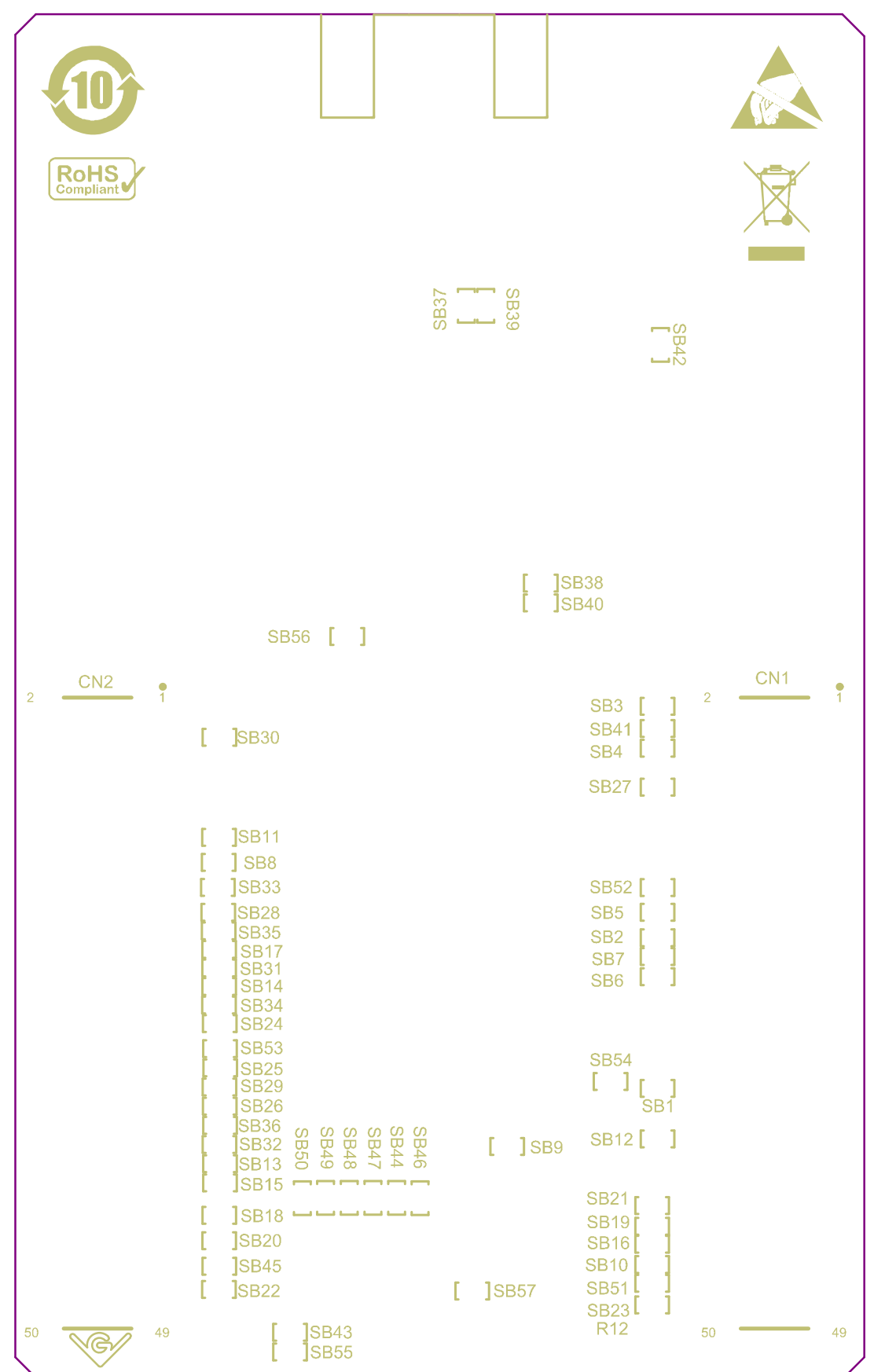
Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Int6 (Sign)	Gerber: .G6	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	




Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	

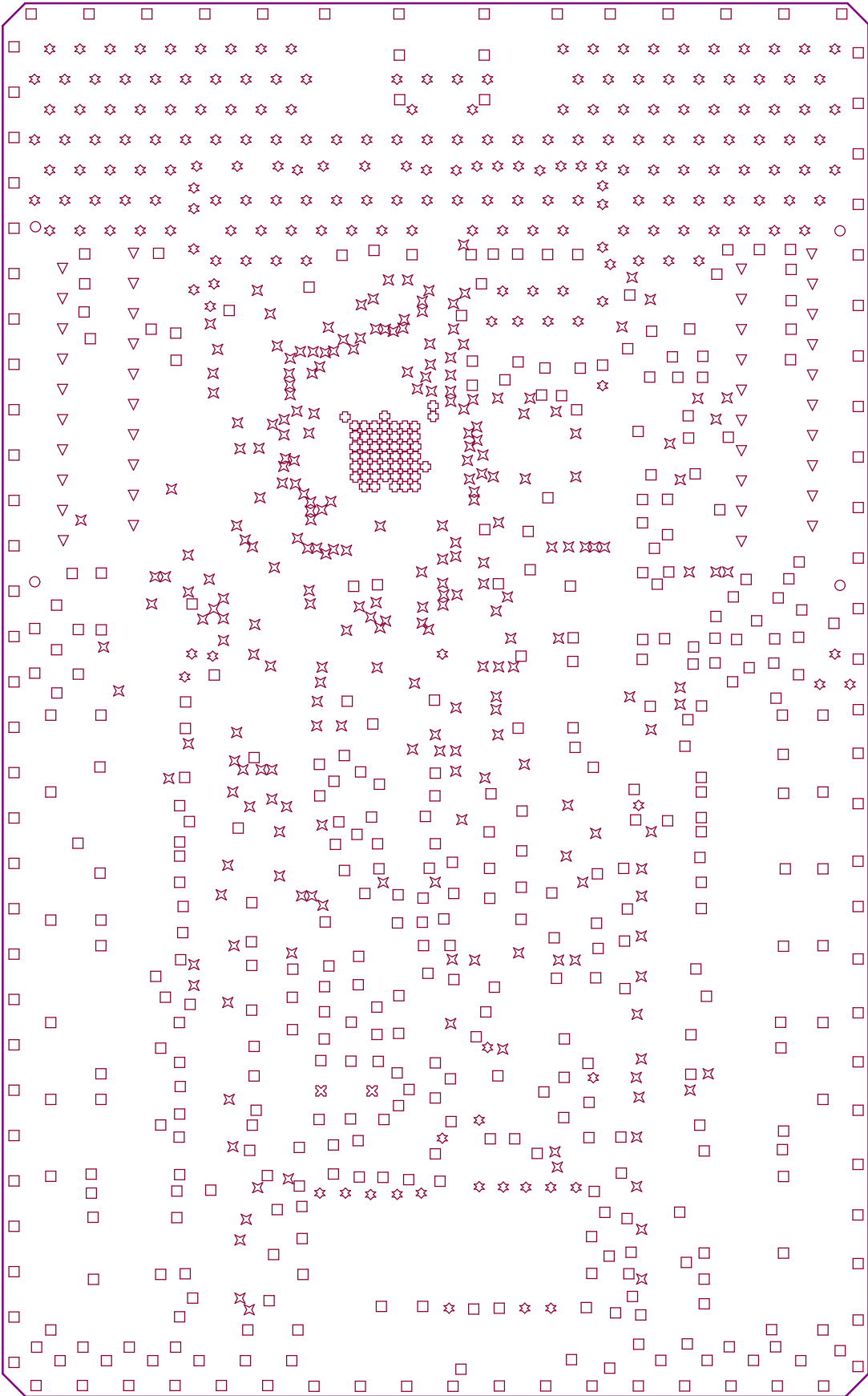



Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	



Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	1.00mil	4	
	Top Surface Finish	PbSn	0.79mil		
1	Top Layer	CF-004	1.38mil		
	Dielectric 1	PP-006	2.80mil	4.1	
2	Int1 (Sign)	CF-004	1.38mil		
	Dielectric 6	PP-006	2.80mil	4.1	
3	Int2 (Sign)	CF-004	1.38mil		
	Dielectric 2	Core-035	18.00mil	4.7	
4	Int3 (Sign)	CF-004	1.38mil		
	Dielectric 3	Core-015	5.00mil	4.4	
5	Int4 (Sign)	CF-004	1.38mil		
	Dielectric 4	Core-035	18.00mil	4.7	
6	Int5 (Sign)	CF-004	1.38mil		
	Dielectric 7	PP-006	2.80mil	4.1	
7	Int6 (Sign)	CF-004	1.38mil		
	Dielectric 5	PP-006	2.80mil	4.1	
8	Bottom Layer	CF-004	1.38mil		
	Bottom Surface Finish	PbSn	0.79mil		
	Bottom Solder	SM-001	1.00mil	4	
	Bottom Overlay				



Project: MB2327_Miniboard_STM32WBA65PII6_BGA121		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2327	
Date: 07-10-2024	Rev: A	